

# Air Release Additives for Epoxy and PUR Systems

## Composition

BYK-A 506	Solution of foam destroying polysiloxanes
BYK-A 525	Solution of a polyether modified methylalkylpolysiloxane copolymer
BYK-A 530	Solution of foam destroying polymers and polysiloxanes

## Typical Physical Data

	Density at 20°C in g/ml	Non-volatile matter in %	Flash point in °C	Refractive index	Appearance
BYK-A 506	0,95	0,7	43	1,450	clear, light yellow liquid
BYK-A 525	0,86	52	38	1,441	clear to slightly turbid colorless to yellowish liquid
BYK-A 530	0,81	5	95	1,448	clear to slightly turbid, colorless to yellowish liquid
	Values indicated in this data sheet describe typical properties and do not constitute specification limits.				

### **Recommended Amounts**

	% additive (delivery form) based upon:
	Total formulation weight
BYK-A 506	0,1 – 1,0
BYK-A 525	0,1 – 0,5
BYK-A 530	0,5 – 2,0

#### Incorporation Methods and Processing Instructions

In order to prevent air entrapment and foam during manufacture and/or application, the additives should be stirred into the resin prior to the addition of other ingredients. Post-addition is also possible.

### **Application Fields**

	Epoxy resins	PUR resins
BYK-A 506	•	•
BYK-A 525	•	О
BYK-A 530	•	O
	<ul><li>excellent</li></ul>	⊙ good

### Special Properties and Advantages

BYK-A 506	is used to prevent foam and bubble formation during the manufacture and application of epoxy and polyurethane systems.
BYK-A 525	is used to prevent air inclusions and porosity in epoxy and polyurethane systems. In quartz filled epoxy resins it shows excellent air release properties and is often used in combination with BYK-A 500.
BYK-A 530	is an effective air release additive to prevent foaming during manufacture and application of epoxy resin systems, so that systems free from blisters and pinholes with smooth surfaces are achieved.

## **Packaging**

Drums and pails

Containers not completely emptied must be closed immediately after use!



This information is given to the best of our knowledge. Because of the multitude of formulations, production and application conditions, all the above mentioned statements have to be adjusted to the circumstances of the processor. No liabilities, including those for patent rights, can be derived from this fact for individual cases.

09/01 - This data sheet replaces all previous issues - Printed in Germany